

# MaxVIA™ Plasma System

## Features and Benefits

- High throughput of HDI, flexible and rigid panels for maximum production flexibility
- Accommodates multiple panel sizes within a small footprint to consume minimal floor space
- Fast units per hour (UPH) processing to meet today's demanding manufacturing schedules
- Low CF4 gas consumption for desmear applications, contributes to the lowest cost of ownership in its class
- Patented system technologies produce superior process uniformity at high throughput

## Superior Plasma Uniformity for High Throughput PCB Treatment

Nordson MARCH's MaxVIA™ system is specifically configured to meet the demands of today's high throughput PCB manufacturing operations. Plasma treatment uniformity is a key operational feature in desmear and etch back applications for HDI, flexible and rigid circuit board manufacturing technologies. The MaxVIA system delivers!

The MaxVIA system platform is completely self-contained, requiring minimal floor space. The vacuum system, plasma chamber, control electronics, and 40 kHz power supply are housed in a single enclosure. Full front and rear access allows for convenient service to all interior components. The pump is positioned on rollers for easy removal. No side access is required allowing for even greater floor space savings.

## Application Specific Technology

The MaxVIA system incorporates the best of Nordson MARCH's market leading technology combined with novel application specific technology development based



on our greater than 25 years of experience. Through extensive research and development, the MaxVIA system presents unique vacuum and gas flow technology, new electrode designs, and superior temperature management. The careful balance of these critical design elements and process recipe parameters delivers a system that creates the most uniform PCB treatment for key applications like desmear and landing pad cleaning.

The MaxVIA system's superior performance capabilities are complemented by very attractive low-cost-of-ownership aspects. The system features a very compact and service-friendly design. The vertical loading concept and the use of easy loading carts minimizes any idle time which generates high levels of productivity. The fast vacuum pump down and greatly enhanced process cycle times further add to the throughput and productivity of the system.

Equipped with a touch-screen PC Operator Interface, the MaxVIA system provides a wide breadth of control capability and data collection. Unlimited recipes can be stored for easy switching of plasma processes from batch to batch. Password protection ensures that no unauthorized entries can be made.



## Specifications: MaxVIA™ Plasma System

<b>Enclosure Dimensions</b>	<b>W x D x H – Footprint</b>	1652W x 1747D x 2445H mm (65W x 69D x 97H in.)
	<b>Net Weight</b>	2330 kg (5137 lbs)
<b>Chamber</b>	<b>Number of Available Cells</b>	13
<b>Electrodes</b>	<b>Configuration</b>	Temperature Controlled Power-Power
	<b>Working Area</b>	1118D x 610H mm; (44D x 24H in.)
<b>RF Power</b>	<b>Standard Wattage</b>	10 kW
	<b>Frequency</b>	40 kHz
<b>Gas Control</b>	<b>Available Flow Volumes</b>	500, 1000, 2000 or 5000 sccms
	<b>Maximum Number of MFCs</b>	5
<b>Control</b>	<b>Interface</b>	EPC with PC-Based Touch Screen Interface
<b>Vacuum Pump</b>	<b>Standard Purged Pump Package</b>	530 cfm
	<b>Cooling Water Flow</b>	9.5 slm
	<b>N2 Pump Purge Flow</b>	14 slm
<b>Facilities</b>	<b>Power Supply</b>	208 VAC, 50 A, 3-Phase + Ground; 50/60 Hz
	<b>Process Gas Fitting Size &amp; Type</b>	6.35 mm (0.25 in.) Swagelok
	<b>Process Gas Purity</b>	CF4 = 99.97%; O2 = 99.996%; N2 = 99.99%; Ar = 99.999%; H2 = 99.999%
	<b>Process Gas Pressure</b>	1.03 bar (15 psig) min. to 1.7 bar (25 psig) max., regulated
	<b>Purge Gas Fitting Size &amp; Type</b>	9.5 mm (0.375 in.) Swagelok Tube
	<b>Purge Gas Purity</b>	N2 = 99.99%
	<b>Purge Gas Pressure</b>	1.03 bar (15 psig) min. to 1.7 bar (25 psig) max., regulated
	<b>Pneumatic Valves Fitting Size &amp; Type</b>	9.5 mm (0.375 in.) Swagelok
	<b>Pneumatic Gas Purity</b>	CDA, Oil Free, Dewpoint ≤7°C (45°F), Particulate Size <5 µm
	<b>Pneumatic Gas Pressure</b>	6.2 bar (90 psig) min. to 6.9 bar (100 psig) max., regulated
<b>Compliance</b>	<b>USA</b>	EH&S/Ergonomics
	<b>International</b>	CE Marked
<b>Ancillary Equipment</b>	<b>Gas Generators</b>	Nitrogen, Hydrogen (requires Additional Non-Optional Hardware)
	<b>Facilities</b>	Chiller, Scrubber, Transformer

**For more information, speak with your local representative or contact your regional office.**

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Published 2018-03-09

